

1.	Record Nr.	UNINA9910155591603321
	Titolo	Private: The Royals : The BookShots Line
	Pubbl/distr/stampa	Blackstone Audio
	ISBN	1-4789-1802-0
	Lingua di pubblicazione	Inglese
	Formato	Musica
	Livello bibliografico	Monografia
2.	Record Nr.	UNINA9910963455303321
	Titolo	Lead-free solder interconnect reliability / / edited by Dongkai Shangguan
	Pubbl/distr/stampa	Materials Park, OH, : ASM International, 2005
	ISBN	1-61503-093-X
	Edizione	[1st ed.]
	Descrizione fisica	1 online resource (302 p.)
	Altri autori (Persone)	ShangguanDongkai <1963->
	Disciplina	621.381/046
	Soggetti	Microelectronic packaging - Reliability Solder and soldering Lead-free electronics manufacturing processes
	Lingua di pubblicazione	Inglese
	Formato	Materiale a stampa
	Livello bibliografico	Monografia
	Note generali	Description based upon print version of record.
	Nota di bibliografia	Includes bibliographical references and index.
	Nota di contenuto	""Contents""; ""Foreword""; ""Preface""; ""Lead-Free Soldering and Environmental Compliance: An Overview""; ""Microstructural Evolution and Interfacial Interactions in Lead-Free Solder Interconnects""; ""Fatigue and Creep of Lead-Free Solder Alloys: Fundamental Properties""; ""Lead-Free Solder Joint Reliability Trends""; ""Chemical Interactions and Reliability Testing for Lead-Free Solder Interconnects""; ""Tin Whisker Growth on Lead-Free Solder Finishes""; ""Accelerated Testing Methodology for Lead-Free Solder Interconnects"" ""Thermomechanical Reliability Prediction of Lead-Free Solder Interconnects"" ""Design for Reliability Finite Element Modeling of Lead-

Free Solder Interconnects"; "Characterization and Failure Analyses of Lead-Free Solder Defects"; "Reliability of Interconnects with Conductive Adhesives"; "Lead-Free Solder Interconnect Reliability Outlook"; "Index"

Sommario/riassunto

This book provides the most up-to-date knowledge and data available on the reliability of lead-free solder interconnects. The content has been written by leading experts working in this important technology area. Both fundamental research and practical considerations are addressed. Environmental regulations are driving the worldwide adoption of lead-free soldering technology for electronics packaging, board assembly, and related manufacturing operations. While a significant amount of research and development work has been conducted in recent years on manufacturing issues to enable the conversion to lead-free solders, data from studies related to the reliability of lead-free solder interconnects are still emerging. Many research projects around the world have been undertaken to study lead-free solder reliability under different loading conditions. This book is the first comprehensive guide to reliability of lead-free solder interconnects.
